

REMARKS/ARGUMENTS

Claims 1, 10, and 11 have been amended, and claims 14-16 have been newly added. In addition, claim 13 has been canceled without prejudice. Claims 1-12 and 14-16 are now pending in the application. Applicants respectfully request reexamination and reconsideration of the application as amended.

As an initial matter, an information disclosure statement is enclosed with this paper, thereby addressing the Examiner's concern over cited references.

The title, abstract, and specification were objected to. In addition, claims 10 and 11 were rejected under 35 USC § 112, second paragraph. Applicants have amended the title, abstract, specification, and claims 10 and 11 to address the Examiner's concerns and believe that the objection to the title, abstract, and specification and the rejection of claims 10 and 11 have been overcome.

Claims 1-7, 10-11, and 13 were rejected under 35 U.S.C. § 102(b) or in the alternative 35 U.S.C. § 103(a) over Chan (U.S. Patent 4,983,804). In addition, claims 8 and 9 were rejected as obvious in view of Chan, and claim 12 was rejected as obvious in view of Chan and US Patent No. 5,340,537. Applicants respectfully traverse these rejections.

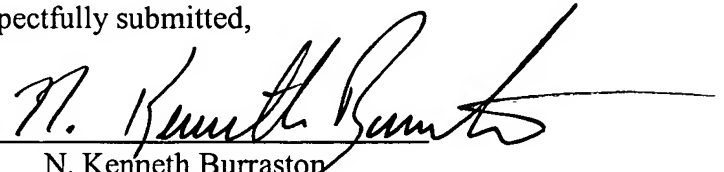
Independent claim 1 is directed to a method of heat treating a plurality of microelectronic structures attached to a non-metallic substrate. An oscillating electromagnetic field heats the microelectronic structures to heat treat them and thereby improve a mechanical operating property of the microelectronic structures. New dependent claim 16 specifies that the improved mechanical operating property is at least one of "improved yield strength, improved resiliency to fatigue, decreased brittleness, or improved hardness." Chan, on the other hand, merely discloses heating solder to melt the solder. Nothing in Chan teaches or suggests heat treating microelectronic structures to improve a mechanical operating property of the structures. None of the other cited art makes up for this deficiency in Chan. Therefore, independent claim 1 as well as claims 2-12 and 14-16, all of which depend from claim 1, patentably distinguish over Chan and the other cited references.

For all of the above reasons Applicant respectfully requests withdrawal of the rejections and the objections and allowance of the application. If the Examiner believes that a discussion with Applicants' attorney would be helpful, the Examiner is invited to contact the undersigned at (801) 536-6763.

Respectfully submitted,

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By



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